

演講者簡歷 Speaker's curriculum vitae

姓名 Name	Tung-Yi, Chan	
現職 Current position	Winbond Electronics corp. Vice Chairman & Deputy CEO	
專長領域 Field of Specialization	<p>Tung-Yi has been the president of Winbond Electronics Corp. in 2009 – 2020, a world leading code storage Flash supplier and one of the major suppliers in specialty DRAM. He has worked in Intel in advanced MOSFET device technology, Cypress in SRAM and EPROM technologies, and Siliconix in power device technologies. He has been CEO of BCD Semiconductor in Shanghai China, an IDM in power devices. He is currently vice chairman and deputy CEO of Winbond Electronics Corp. Through work in those companies and different geographic area, Tung-Yi accumulated wide experience in technology development, marketing, sales, and business management.</p>	
演講題目 Speech Topic(s)	<p>台灣資安技術、產業生態系及國際合作 Taiwan Cybersecurity Technology, Industry Ecosystem and International Cooperation</p>	
主要經歷 Working Experience	<ul style="list-style-type: none"> • President, Winbond Electronics Corp. • CEO, BCD Semiconductor • Vice President of Sales Center, Winbond Electronics Corp. • Technology Manager, Siliconix • Technology Manager, Cypress • Senior Engineer, Intel 	
近期研究 Recent Research		
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